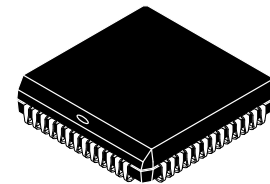


MCM67H618B

Advance Information
64K x 18 Bit BurstRAM
Synchronous Fast Static RAM
With Burst Counter and Self-Timed Write



FN PACKAGE
PLASTIC
CASE 778-02

The MCM67H618B is a 1,179,648 bit synchronous fast static random access memory designed to provide a burstable, high-performance, secondary cache for the i486™ and Pentium™ microprocessors. It is organized as 65,536 words of 18 bits, fabricated with Motorola's high-performance silicon-gate BiCMOS technology. The device integrates input registers, a 2-bit counter, high speed SRAM, and high drive capability outputs onto a single monolithic circuit for reduced parts count implementation of cache data RAM applications. Synchronous design allows precise cycle control with the use of an external clock (K). BiCMOS circuitry reduces the overall power consumption of the integrated functions for greater reliability.

Addresses (A0 – A15), data inputs (D0 – D17), and all control signals except output enable (G) are clock (K) controlled through positive-edge-triggered noninverting registers.

Bursts can be initiated with either address status processor (ADSP) or address status cache controller (ADSC) input pins. Subsequent burst addresses can be generated internally by the MCM67H618B (burst sequence imitates that of the i486 and Pentium) and controlled by the burst address advance (ADV) input pin. The following pages provide more detailed information on burst controls.

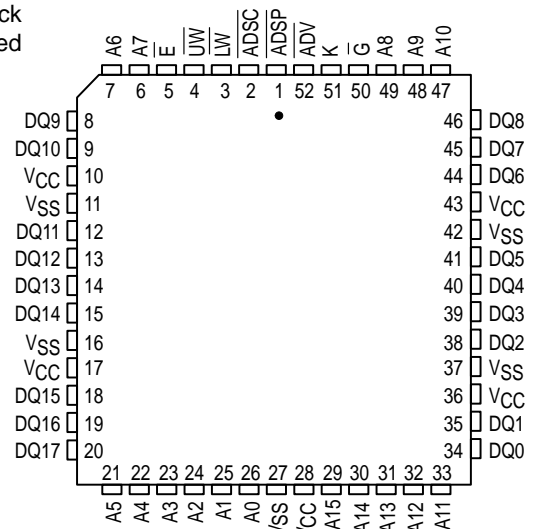
Write cycles are internally self-timed and are initiated by the rising edge of the clock (K) input. This feature eliminates complex off-chip write pulse generation and provides increased flexibility for incoming signals.

Dual write enables (LW and UW) are provided to allow individually writable bytes. LW controls DQ0 – DQ8 (the lower bits), while UW controls DQ9 – DQ17 (the upper bits).

This device is ideally suited for systems that require wide data bus widths and cache memory. See Figure 2 for applications information.

- Single 5 V ± 5% Power Supply
- Fast Access Times: 9/10/12 ns Max
- Byte Writeable via Dual Write Enables
- Internal Input Registers (Address, Data, Control)
- Internally Self-Timed Write Cycle
- ADSP, ADSC, and ADV Burst Control Pins
- Asynchronous Output Enable Controlled Three-State Outputs
- Common Data Inputs and Data Outputs
- 3.3 V I/O Compatible
- High Board Density 52-Lead PLCC Package
- ADSP Disabled with Chip Enable (E) — Supports Address Pipelining

PIN ASSIGNMENT



PIN NAMES

A0 – A15	Address Inputs
K	Clock
ADV	Burst Address Advance
LW	Lower Byte Write Enable
UW	Upper Byte Write Enable
ADSC	Controller Address Status
ADSP	Processor Address Status
E	Chip Enable
G	Output Enable
DQ0 – DQ17	Data Input/Output
VCC	+ 5 V Power Supply
VSS	Ground

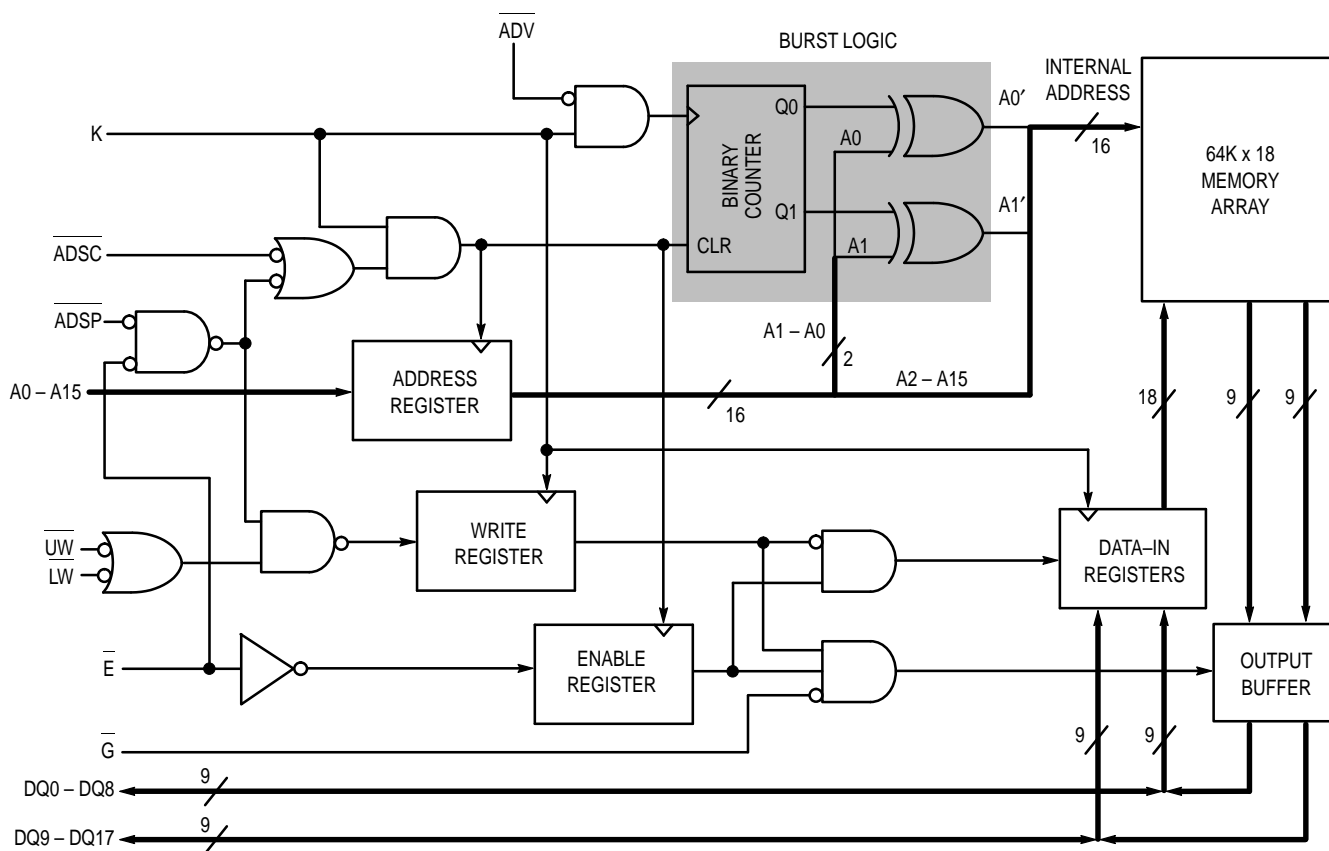
All power supply and ground pins must be connected for proper operation of the device.

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This document contains information on a new product. Specifications and information herein are subject to change without notice.

REV 1
7/15/97

BLOCK DIAGRAM (See Note)



NOTE: All registers are positive-edge triggered. The $\overline{\text{ADSC}}$ or $\overline{\text{ADSP}}$ signals control the duration of the burst and the start of the next burst. When $\overline{\text{ADSP}}$ and $\overline{\text{E}}$ are sampled low, any ongoing burst is interrupted and a read (independent of $\overline{\text{W}}$ and $\overline{\text{ADSC}}$) is performed using the new external address. Alternatively, an $\overline{\text{ADSP}}$ -initiated two cycle **WRITE** can be performed by asserting $\overline{\text{ADSP}}$, $\overline{\text{E}}$, and a valid address on the first cycle, then negating both $\overline{\text{ADSP}}$ and $\overline{\text{ADSC}}$ and asserting $\overline{\text{LW}}$ and/or $\overline{\text{UW}}$ with valid data on the second cycle (see Single Write Cycle in **WRITE CYCLES** timing diagram). Note that when $\overline{\text{E}}$ and $\overline{\text{ADSC}}$ are high, $\overline{\text{ADSP}}$ is ignored — the external address is not registered in this case.

When $\overline{\text{ADSC}}$ is sampled low (and $\overline{\text{ADSP}}$ is sampled high), any ongoing burst is interrupted and a read or write (dependent on $\overline{\text{W}}$) is performed using the new external address. Chip enable ($\overline{\text{E}}$) is sampled only when a new base address is loaded. After the first cycle of the burst, $\overline{\text{ADV}}$ controls subsequent burst cycles. When $\overline{\text{ADV}}$ is sampled low, the internal address is advanced prior to the operation. When $\overline{\text{ADV}}$ is sampled high, the internal address is not advanced, thus inserting a wait state into the burst sequence accesses. Upon completion of a burst, the address will wrap around to its initial state. See **BURST SEQUENCE TABLE**. Write refers to either or both byte write enables ($\overline{\text{LW}}$, $\overline{\text{UW}}$).

BURST SEQUENCE TABLE (See Note)

External Address	A15 – A2	A1	A0
1st Burst Address	A15 – A2	A1	A0
2nd Burst Address	A15 – A2	A1	A0
3rd Burst Address	A15 – A2	A1	A0

NOTE: The burst wraps around to its initial state upon completion.

SYNCHRONOUS TRUTH TABLE (See Notes 1, 2, and 3)

E	ADSP	ADSC	ADV	UW or LW	K	Address Used	Operation
H	X	L	X	X	L-H	N/A	Deselected
L	L	X	X	X	L-H	External Address	Read Cycle, Begin Burst
L	H	L	X	L	L-H	External Address	Write Cycle, Begin Burst
L	H	L	X	H	L-H	External Address	Read Cycle, Begin Burst
X	H	H	L	L	L-H	Next Address	Write Cycle, Continue Burst
X	H	H	L	H	L-H	Next Address	Read Cycle, Continue Burst
X	H	H	H	L	L-H	Current Address	Write Cycle, Suspend Burst
X	H	H	H	H	L-H	Current Address	Read Cycle, Suspend Burst
H	X	H	L	L	L-H	Next Address	Write Cycle, Continue Burst
H	X	H	L	H	L-H	Next Address	Read Cycle, Continue Burst
H	X	H	H	L	L-H	Current Address	Write Cycle, Suspend Burst
H	X	H	H	H	L-H	Current Address	Read Cycle, Suspend Burst

NOTES:

1. X means Don't Care.
2. All inputs except G must meet setup and hold times for the low-to-high transition of clock (K).
3. Wait states are inserted by suspending burst.

ASYNCHRONOUS TRUTH TABLE (See Notes 1 and 2)

Operation	G	I/O Status
Read	L	Data Out
Read	H	High-Z
Write	X	High-Z — Data In
Deselected	X	High-Z

NOTES:

1. X means Don't Care.
2. For a write operation following a read operation, G must be high before the input data required setup time and held high through the input data hold time.

ABSOLUTE MAXIMUM RATINGS (Voltages Referenced to $V_{SS} = 0$ V)

Rating	Symbol	Value	Unit
Power Supply Voltage	V_{CC}	- 0.5 to + 7.0	V
Voltage Relative to V_{SS} for Any Pin Except V_{CC}	V_{in}, V_{out}	- 0.5 to $V_{CC} + 0.5$	V
Output Current (per I/O)	I_{out}	± 30	mA
Power Dissipation	P_D	1.6	W
Temperature Under Bias	T_{bias}	- 10 to + 85	°C
Ambient Temperature	T_A	0 to +70	°C
Storage Temperature	T_{stg}	- 55 to + 125	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

This BiCMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established.

This device contains circuitry that will ensure the output devices are in High-Z at power up.

DC OPERATING CONDITIONS AND CHARACTERISTICS

($V_{CC} = 5.0 \text{ V} \pm 5\%$, $T_A = 0 \text{ to } +70^\circ\text{C}$, Unless Otherwise Noted)

RECOMMENDED OPERATING CONDITIONS (Voltages Referenced to $V_{SS} = 0 \text{ V}$)

Parameter	Symbol	Min	Max	Unit
Supply Voltage (Operating Voltage Range)	V_{CC}	4.75	5.25	V
Input High Voltage	V_{IH}	2.2	$V_{CC} + 0.3^{**}$	V
Input Low Voltage	V_{IL}	-0.5*	0.8	V

* $V_{IL} \text{ (min)} = -0.5 \text{ V dc}$; $V_{IL} \text{ (min)} = -2.0 \text{ V ac}$ (pulse width $\leq 20.0 \text{ ns}$) for $I \leq 20.0 \text{ mA}$.

** $V_{IH} \text{ (max)} = V_{CC} + 0.3 \text{ V dc}$; $V_{IH} \text{ (max)} = V_{CC} + 2.0 \text{ V ac}$ (pulse width $\leq 20.0 \text{ ns}$) for $I \leq 20.0 \text{ mA}$.

DC CHARACTERISTICS AND SUPPLY CURRENTS

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, $V_{in} = 0 \text{ to } V_{CC}$)	$I_{kg(I)}$	—	± 1.0	μA
Output Leakage Current ($G = V_{IH}$)	$I_{kg(O)}$	—	± 1.0	μA
AC Supply Current (Device Selected, All Outputs Open, Freq = Max)	I_{CCA}	—	TBD	mA
	MCM67H618B-9 MCM67H618B-10 MCM67H618B-12			
CMOS Standby Supply Current (Device Deselected, Freq = 0, $V_{CC} = \text{Max}$, All Inputs Static at CMOS Levels $V_{in} \leq V_{SS} + 0.2 \text{ V}$ or $\geq V_{CC} - 0.2 \text{ V}$)	I_{SB2}	—	TBD	mA
Clock Running (Device Deselected, Freq = Max, $V_{CC} = \text{Max}$, All Inputs Toggling at CMOS Levels $V_{in} \leq V_{SS} + 0.2 \text{ V}$ or $\geq V_{CC} - 0.2 \text{ V}$)	I_{SB4}	—	TBD	mA
Output Low Voltage ($I_{OL} = +8.0 \text{ mA}$)	V_{OL}	—	0.4	V
Output High Voltage ($I_{OH} = -4.0 \text{ mA}$)	V_{OH}	2.4	3.3	V

NOTE: Good decoupling of the local power supply should always be used. DC characteristics are guaranteed for all possible i486 and Pentium bus cycles.

CAPACITANCE (f = 1.0 MHz, dV = 3.0 V, $T_A = 25^\circ\text{C}$, Periodically Sampled Rather Than 100% Tested)

Parameter	Symbol	Typ	Max	Unit
Input Capacitance	C_{in}	4	5	pF
Input/Output Capacitance	$C_{I/O}$	6	8	pF

AC OPERATING CONDITIONS AND CHARACTERISTICS

($V_{CC} = 5.0\text{ V} \pm 5\%$, $T_A = 0\text{ to } +70^\circ\text{C}$, Unless Otherwise Noted)

Input Timing Measurement Reference Level 1.5 V
 Input Pulse Levels 0 to 3.0 V
 Input Rise/Fall Time 3 ns

Output Timing Reference Level 1.5 V
 Output Load See Figure 1 Unless Otherwise Noted

READ/WRITE CYCLE TIMING (See Notes 1, 2, 3, and 4)

Parameter	Symbol	MCM67H618B-9		MCM67H618B-10		MCM67H618B-12		Unit	Notes	
		Min	Max	Min	Max	Min	Max			
Cycle Time	t_{KHKH}	15	—	16.6	—	20	—	ns		
Clock Access Time	t_{KHQV}	—	9	—	10	—	12	ns	5	
Output Enable to Output Valid	t_{GLQV}	—	5	—	5	—	6	ns		
Clock High to Output Active	t_{KHQX1}	6	—	6	—	6	—	ns		
Clock High to Output Change	t_{KHQX2}	3	—	3	—	3	—	ns		
Output Enable to Output Active	t_{GLQX}	0	—	0	—	0	—	ns		
Output Disable to Q High-Z	t_{GHQZ}	—	6	—	7	—	7	ns	6	
Clock High to Q High-Z	t_{KHQZ}	3	6	3	7	3	7	ns		
Clock High Pulse Width	t_{KHKL}	5	—	5	—	6	—	ns		
Clock Low Pulse Width	t_{KLKH}	5	—	5	—	6	—	ns		
Setup Times:	Address	t_{AVKH}	2.5	—	2.5	—	2.5	—	ns	7
	Address Status	t_{ADSVKH}								
	Data In	t_{DVKH}								
	Write	t_{WVKH}								
	Address Advance	t_{ADVVKH}								
	Chip Enable	t_{EVKH}								
Hold Times:	Address	t_{KHAX}	0.5	—	0.5	—	0.5	—	ns	7
	Address Status	t_{KHADSX}								
	Data In	t_{KHDX}								
	Write	$t_{KH WX}$								
	Address Advance	t_{KHADVX}								
	Chip Enable	t_{KHEX}								

NOTES:

- In setup and hold times, W (write) refers to either one or both byte write enables \overline{LW} and \overline{UW} .
- A read cycle is defined by \overline{UW} and \overline{LW} high or \overline{ADSP} low for the setup and hold times. A write cycle is defined by \overline{LW} or \overline{UW} low and \overline{ADSP} high for the setup and hold times.
- All read and write cycle timings are referenced from K or \overline{G} .
- \overline{G} is a don't care when \overline{UW} or \overline{LW} is sampled low.
- Maximum access times are guaranteed for all possible i486 and Pentium external bus cycles.
- Transition is measured $\pm 500\text{ mV}$ from steady-state voltage. This parameter is sampled rather than 100% tested. At any given voltage and temperature, $t_{KHQZ}\text{ max}$ is less than $t_{KHQZ1}\text{ min}$ for a given device and from device to device.
- This is a synchronous device. All addresses must meet the specified setup and hold times for **ALL** rising edges of K whenever \overline{ADSP} or \overline{ADSC} is low, and the chip is selected. All other synchronous inputs must meet the specified setup and hold times for **ALL** rising edges of K when the chip is enabled. Chip enable must be asserted at each rising edge of clock for the device (when \overline{ADSC} is low) to remain enabled.

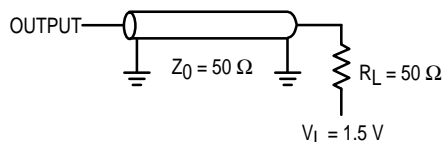
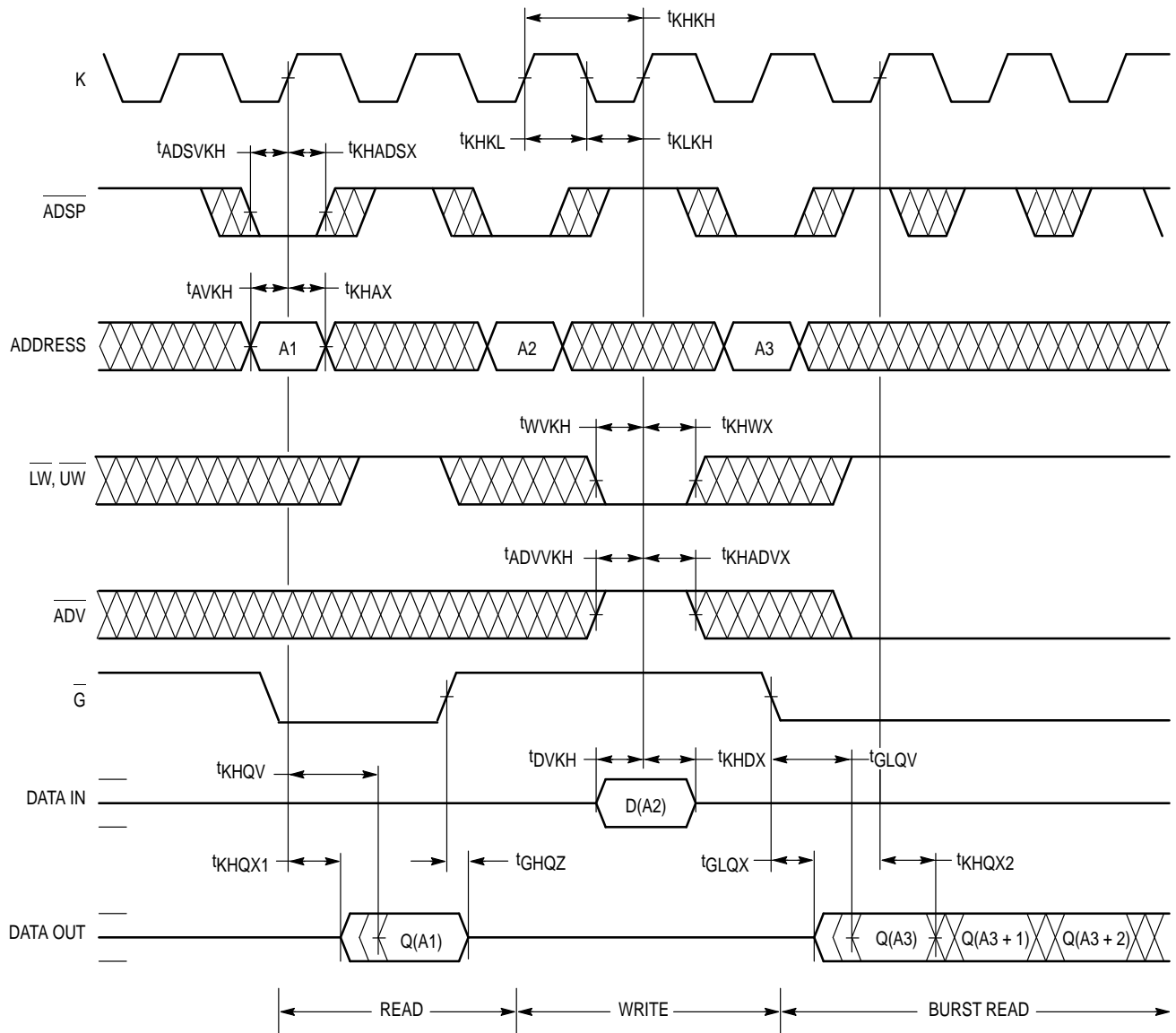
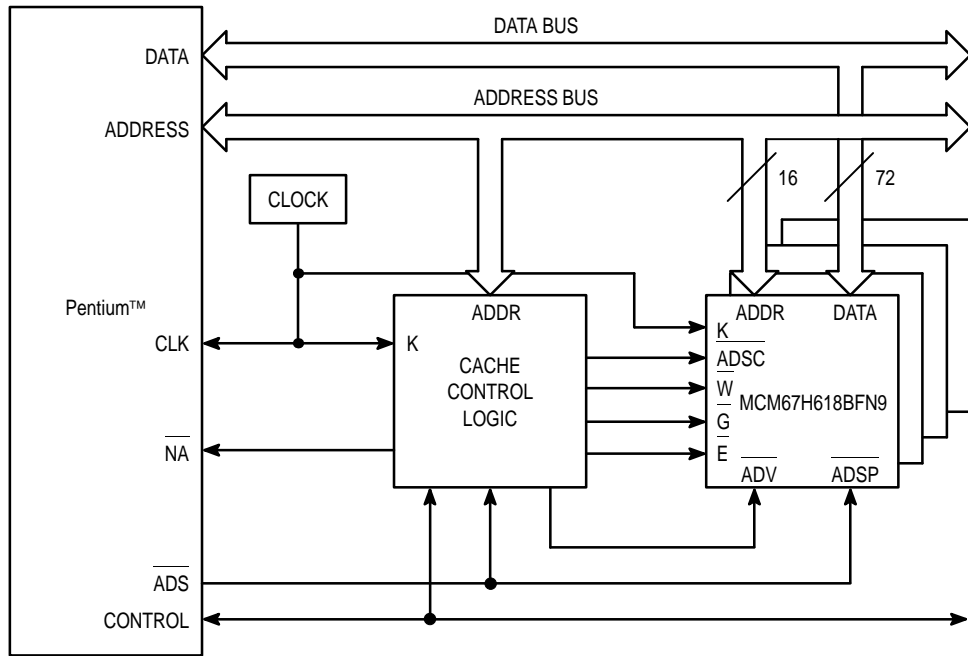


Figure 1. Test Load

COMBINATION READ/WRITE CYCLE (\overline{E} Low, \overline{ADSC} High)



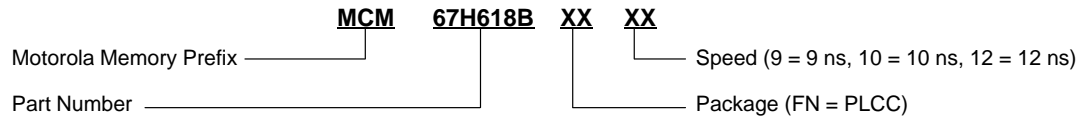
APPLICATION EXAMPLE



512K Byte Burstable, Secondary Cache
Using Four MCM67H618BFN9s with a 66 MHz Pentium

Figure 2.

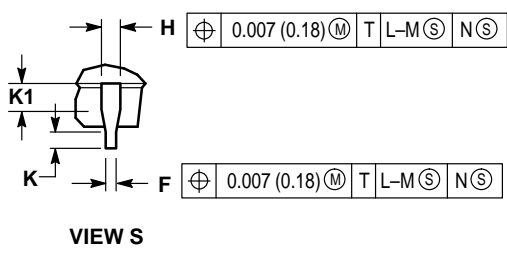
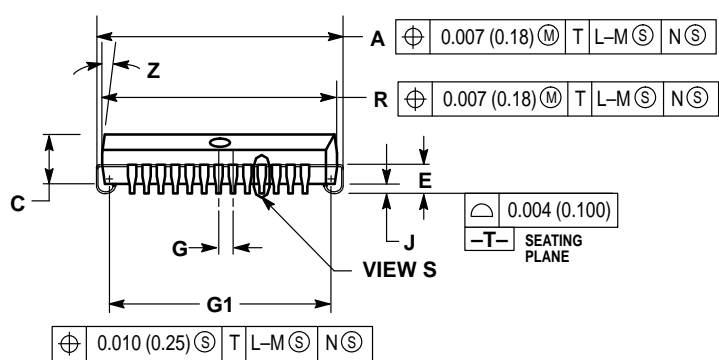
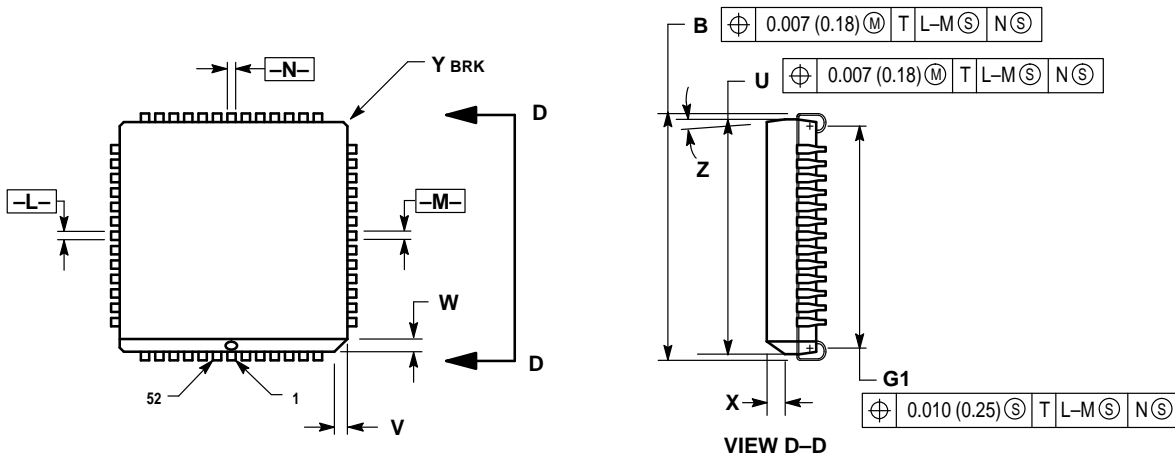
ORDERING INFORMATION
(Order by Full Part Number)



Full Part Numbers — MCM67H618BFN9 MCM67H618BFN10 MCM67H618BFN12


PACKAGE DIMENSIONS

**FN PACKAGE
52-LEAD PLCC
CASE 778-02**



- NOTES:
- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
 - DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
 - DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 - DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: INCH.
 - THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
 - DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.785	0.795	19.94	20.19
B	0.785	0.795	19.94	20.19
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.750	0.756	19.05	19.20
U	0.750	0.756	19.05	19.20
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2° 10°		2° 10°	
G1	0.710	0.730	18.04	18.54
K1	0.040	—	1.02	—

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JAPAN: Nippon Motorola Ltd.; SPD, Strategic Planning Office; 4-32-1,
Nishi-Gotanda; Shinagawa-ku, Tokyo 141, Japan. 81-3-5487-8488

Mfax™: RMFAX0@email.sps.mot.com – TOUCHTONE 602-244-6609
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51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852-26629298

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